

P5000 PE-CVD SOP

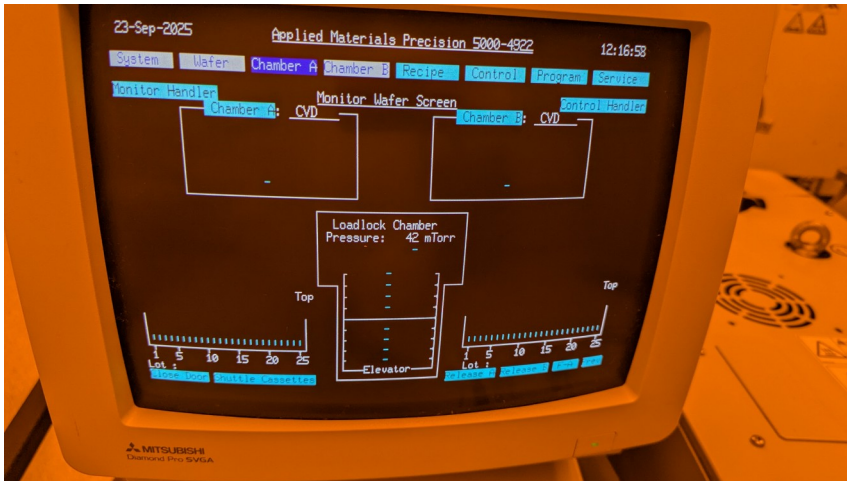
This guide provides a cheat sheet for trained users. DO NOT attempt to operate the machine without proper training. This guide does not give instructions for depositing a-Si. ONLY SiO₂, Si₂N₃ and SiNO.

1: Start scrubber.



2: Find appropriate carrier wafer, if needed. Load carrier or blank 6 inch wafer in one of the blue wafer trays.

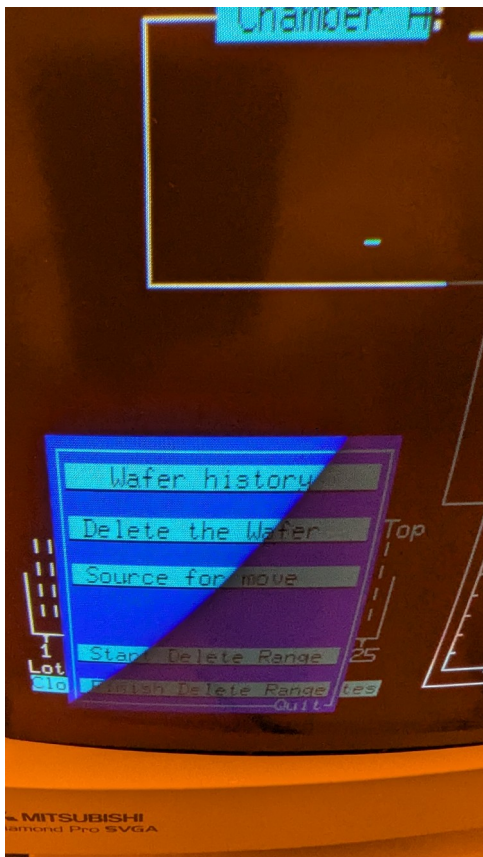
2: With the pen navigate to Wafer>Monitor Wafers. Open the door is needed.



3: Place tray in one of the clamps inside the machine.

4: On the same screen clamp the appropriate holder.

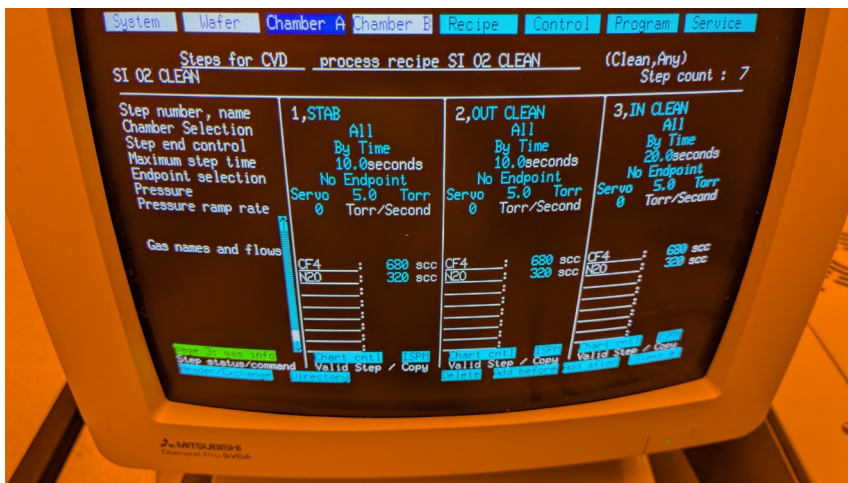
5: Click on the wafer next to the one you loaded on the screen and select Start delete range, click on the last wafer in the tray select End delete range.



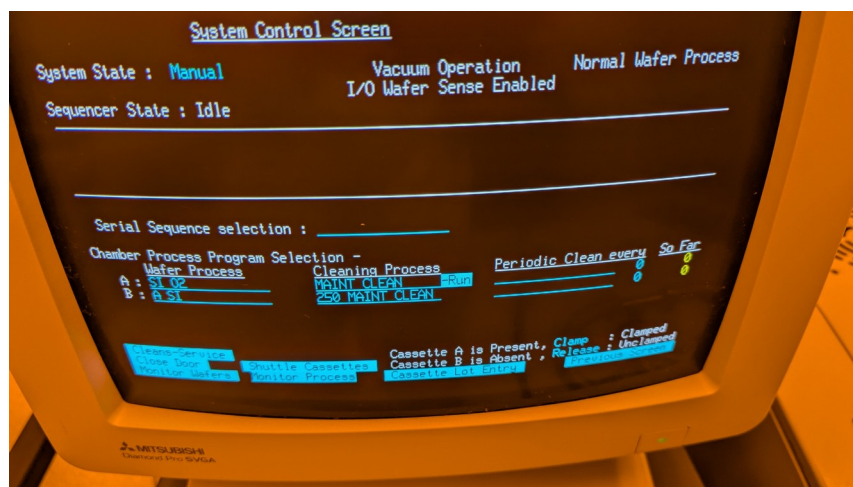
6: Click on your wafer and select Source for move click on an empty slot in the load lock and click Destination for move. Repeat for the the rest of your wafers.

7. Go to the Recipe screen and select the cleaning process appropriate for the material you want to deposit. For example Si O₂ CLEAN.

8. Change the OUT CLEAN to 15 s and the IN CLEAN to 30 s.



9. Navigate to System>Control System, load the cleaning process and run it.



10. Go back to Recipe and select the material recipe you want to use (Si O₂, new SN for nitride or Si O N) and change to time you need for the required thickness.

11. Once the clean is done go back to Wafer>Monitor Wafers and move the wafer into chamber A.

12. Go again to System>Control System load your reposition recipe and once the transfer is done run it.

13. ONLY IF RUNNING MORE THEN ONE WAFER:

Back in Recipe change the clean program you ran before: OUT CLEAN to half of your deposition time and the IN CLEAN to the full deposition time.

14. Back in Recipe change the MAINT CLEAN: OUT CLEAN to half of your deposition time and the IN CLEAN to the full deposition time.

15. When the deposition is done move the wafer back into the load lock.

16. Run the clean process

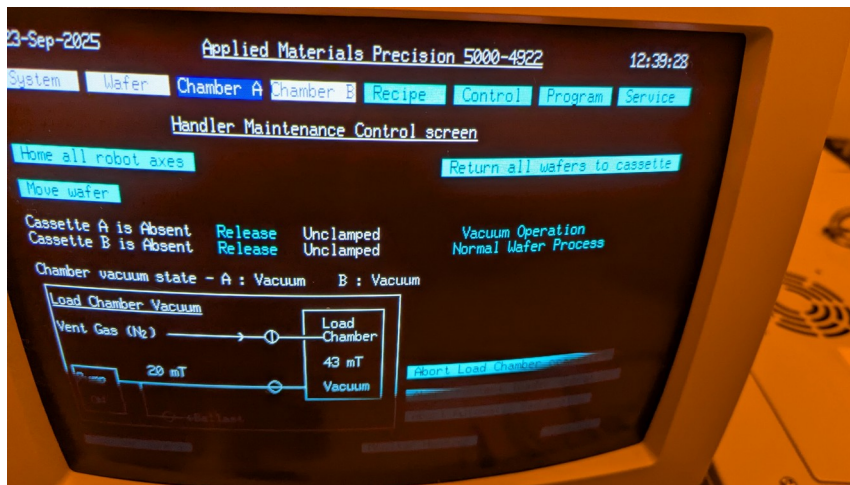
a: If this is the only deposition jump to step 18.

b: If you have more depositions run the the one from step 8.

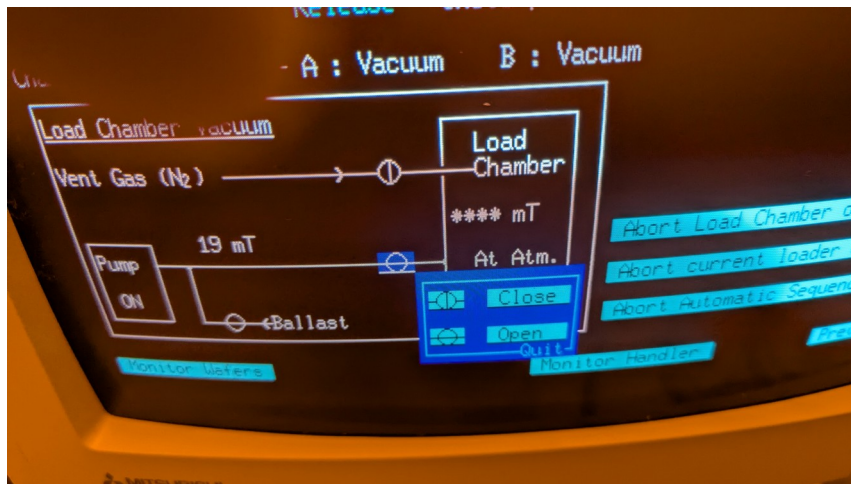
17. Repeat step 11, 15 and 16 till you are done.

18. In System>Control System load MAINT CLEAN and run it.

19. In Wafer>Control Handler select Return all wafers to cassette.



20. Once the wafers are back in the wafer tray open the vacuum valve to the load lock.



21. In Wafer>Monitor Wafers release the clamp.

22. Take your your tray.

23. Wafer>Monitor Wafers close the door.

24. If the clean is done set the scrubber to BYPASS.